Hewlett Packard Enterprise

Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model **[List multiple models if applicable.]**
HPE Altoline 6900 48G 4XG 2QSFP ARM ONIE AC Switch (JL223A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

HPE instructions for this template are available at MF877-01

Item Description	Notes	Quantity of items included in product
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

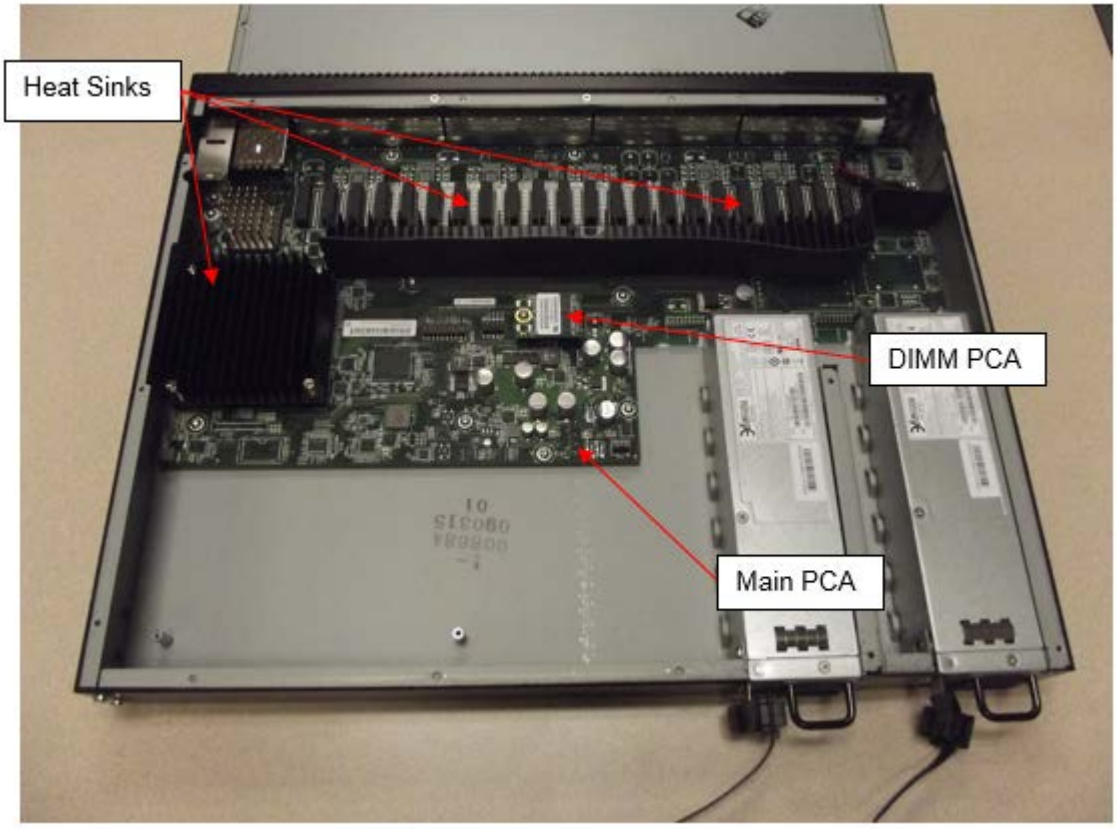
Tool Description	Tool Size (if applicable)
Phillips screwdriver	various sizes
Flat-blade screwdriver	various sizes
Small adjustable wrench	
Needle nose pliers	

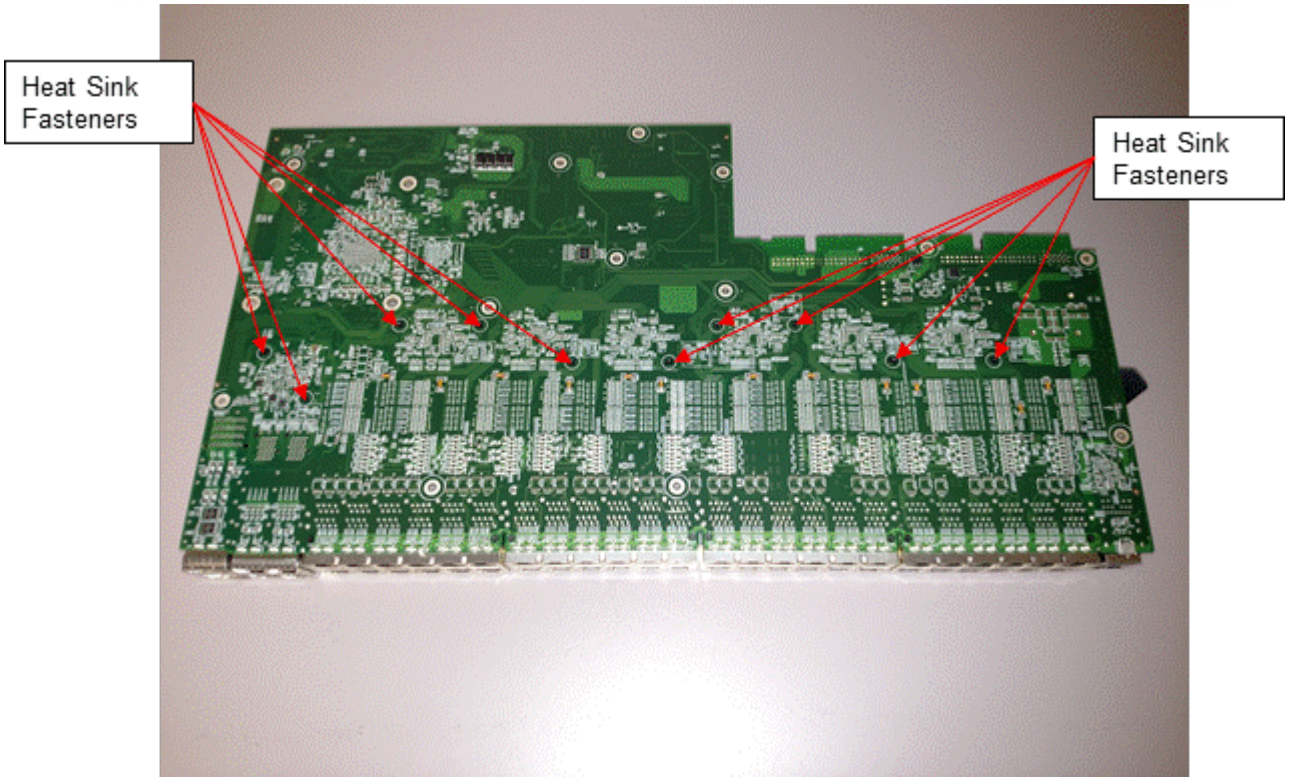
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the chassis lid
    1. Using a Phillips screwdriver, remove the screws (qty 14)
    2. Slide the lid off the chassis
2. Remove the two power supplies
    1. Locate the power supplies on the right side as you are facing the back of the chassis
    2. While pressing the release lever toward the handle, pull the power supply out of the chassis
    3. Repeat for the other power supply
3. Remove the DIMM PCA
    1. Using a Phillips screwdriver, remove the screw securing the small PCA mounted near the center of the main PCA
    2. Remove the DIMM PCA by lifting straight up to disconnect the connector
4. Remove the main PCA
    1. Using a flat-blade screwdriver, loosen the four screws holding down the CPU heat sink
    2. Remove the heat sink
    3. Using a small adjustable wrench, remove the hexagonal studs near the center of the main PCA
    4. Disconnect the front LED cable from the main PCA
    5. Peel the air flow diverter away from the inside wall of the chassis
    6. Using a Phillips screwdriver, remove the twelve screws holding down the main PCA
    7. Slide the main PCA toward the back of the chassis then lift the right side to remove it
5. Remove the remaining three heatsinks
    1. Flip the main PCA over
    2. Use needle nose pliers to pinch the four heat sink fasteners while removing a heat sink from the main PCA
    3. Repeat the above step for the other two heat sinks

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).





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